

Final Product/Process Change Notification

Document # : FPCN21745XA Issue Date: 2 February 2018

Title of Change:	ON Semiconductor Tarlac, Philippines as additional Assembly and Test Site for ESD Protection Diodes - NSPM5131MUTBG			
Proposed first ship date:	9 May 2018 or earlier upon customer approval			
Contact information:	Contact your local ON Semiconductor Sales Office or <mike.begonia@onsemi.com></mike.begonia@onsemi.com>			
Samples:	Contact your local ON Semiconductor Sales Office			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <andy.esteva@onsemi.com></andy.esteva@onsemi.com>			
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>			
Change Part Identification:	Change marking for identification Additional vertical line/bar after one Device NSPM5131MUTBG	digit date code as SBN MA	ARKING	OSPI TARLAC MARKING A3MI
Change category:	☐ Wafer Fab Change ☐ Assem	ably Change	□ Test Change	□ Other
Change Sub-Category(s): Manufacturing Site Change/Addition Manufacturing Process Ch	Material Change Product specific change		☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other:	
Sites Affected:	ON Semiconductor Sites: ON Seremban, Malaysia ON Tarlac City, Philippines		External Foundry/Subcon Sites: None	

Description and Purpose:

The Final Notification announces to customers of the plan to have ON Semiconductor Tarlac, Philippines factory as additional production site for NSPM5131MUTBG which is currently manufactured at ON semiconductor Seremban, Malaysia factory.

The Philippines internal facility is certified with ISO/TS 16949:2009 and is currently running production for DFN packages. These products will continue being Pb-free, Halide free and RoHS compliant. Qualification tests are designed to show that the reliability of the qualified devices will continue to meet or exceed ON Semiconductor standards.

NSPM5131MUTBG

	Before Change (Seremban Build) Description	After Change (Seremban and Tarlac Build) Description
Lead Frame	Selective Ag UDFN 1.8 X 2.0 6L	Selective Ag UDFN 1.8 X 2.0 6L (SBN) PPF UDFN 1.8 X 2.0 6L (TARLAC)
Ероху	AB 8008HT	No change
Mold Compound	MC SU EMEG770	MC SU EMEG770 (SBN) MC SU EMEG760 (TARLAC)
Wire Size/Type	2 mils / PCC	No Change

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Reliability Data Summary:

QV DEVICE NAME: NSPM5131MUTBG

RMS: 41151

PACKAGE: <u>UDFN6, 1.8x2, 0.4P</u>

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	High Temperature Reverse Bias Tj=150C Bias = 100% Vrwm	1008 hrs	0/77*3
HTSL	JESD22-A103	Ta=150C max storafe storage temp for device	2000 hrs	0/77*3
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, deltaTj=100°C max, 2min on/off for 15000 cyc	15000 cyc	0/77*3
TC	JESD22-A104	Temp = -65°C to +150°C; for 1000 cycles	1000 cyc	0/77*3
HAST	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, 100% VRWM for 96hr (JA101)	192 hrs	0/77*3
uHAST	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs	0/77*3
PC	J-STD-020 JESD-A113	IR reflow at 260C		0/480*3
RSH	JESD22- B106	Ta=265C 10 sec dwell B106		0/30*3

Electrical Characteristic Summary:

Data are available upon request.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NSPM5131MUTBG	NSPM5131MUTBG

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Appendix A:	Changed Products		
D			

Product	Customer Part Number	Qualification Vehicle	
NCDM5131MLITEC		NSDM5131MLITEC	